## MSKSEMI



## Features

- 250 Watts peak pulse power ( $\mathrm{tp}=8 / 20 \mu \mathrm{~s}$ )
- Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 30 \mathrm{kV}$ (air), $\pm 30 \mathrm{kV}$ (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- Protects One Power or I/O Port
- Low operating and clamping voltages
- Solid-state silicon avalanche technology


## Applications

- Notebooks, Desktops, Servers and Video Graphics Cards
- USB Power \& Data Line Protection
- Monitors and Flat Panel Displays

- $I^{2} C$ Bus Protection
- Portable Instrumentation
- Set Top Box


## Electrical Characteristics@ Ta=25${ }^{\circ} \mathrm{C}$ unless otherwise

| P/N | VRWM @IR |  | VBR@ImA | Vc@1 | Vc@IPP |  | CJ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | V | $\mu \mathrm{A}$ | V | V | V | A | pF |
|  |  | MAX | MIN | MAX | MAX |  | MAX |
| ESD3V3S1UB-MS | 3.3 | 1 | 4 | 9.8 | 13 | 12 | 120 |
| ESD5V0S1UB-MS | 5 | 1 | 5.8 | 11.8 | 15 | 10 | 100 |
| ESD7V0S1UB-MS | 7 | 1 | 7.5 | 14 | 19 | 8 | 80 |
| ESD12VS1UB-MS | 12 | 1 | 13.3 | 19 | 25 | 6 | 70 |
| ESD15VS1UB-MS | 15 | 1 | 16.5 | 24 | 33 | 5 | 50 |
| ESD24VS1UB-MS | 24 | 1 | 26.1 | 44 | 54 | 3 | 30 |
| ESD36VS1UB-MS | 36 | 1 | 38.2 | 62 | 80 | 3 | 30 |

Maximum Rating @ $\mathrm{Ta}=25^{\circ} \mathrm{C}$ unless otherwise specified

| Symbol | Parameter | Ratings | Units |
| :---: | :--- | :---: | :---: |
| $\mathrm{P}_{\text {PK }}$ | Peak Pulse Power (tp $=8 / 20 \mu \mathrm{~s})$ | 250 | Watts |
| $\mathrm{T}_{\mathrm{L}}$ | Lead Soldering Temperature | $260(10 \mathrm{sec})$. | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{J}$ | Operating Temperature | -55 to +125 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {STG }}$ | Storage Temperature | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

Typical Characteristics@ $\mathrm{Ta}=25^{\circ} \mathrm{C}$ unless otherwise specified



Non-Repetitive Peak Pulse Power vs. Pulse Time



## Soldering Parameters

| Reflow Condition |  | Fb - Free assembly |
| :---: | :---: | :---: |
| Pre Heat | -Temperature Min ( $\mathrm{T}_{\text {s(Min }}$ ) | $150^{\circ} \mathrm{C}$ |
|  | - Temperature Max ( $\mathrm{T}_{\text {s(max) }}$ ) | $200^{\circ} \mathrm{C}$ |
|  | -Time (Min to max) ( $\mathrm{t}_{\mathrm{s}}$ ) | 60-180 secs |
| Average ramp up rate (Liquidus) Temp $\left(T_{L}\right)$ to peak |  | $3^{\circ} \mathrm{C} /$ second Max |
| $\mathrm{T}_{\text {S(Max) }}$ to $\mathrm{T}_{\mathrm{L}}$-Ramp-up Rate |  | $3^{\circ} \mathrm{C} /$ second Max |
| Reflow | -Temperature ( $\mathrm{T}_{L}$ ) (Liquidus) | $217^{\circ} \mathrm{C}$ |
|  | -Temperature ( $\mathrm{t}_{\mathrm{L}}$ ) | 60-150 seconds |
| Peak Temperature ( $\mathrm{T}_{\mathrm{p}}$ ) |  | $250{ }^{+0.5}{ }^{\circ} \mathrm{C}$ |
| Time within $5^{\circ} \mathrm{C}$ of actual peak Temperature ( $\mathrm{t}_{\mathrm{p}}$ ) |  | 20-40 seconds |
| Ramp-dowm Rate |  | $6^{\circ} \mathrm{C} /$ second Max |
| Time $25^{\circ} \mathrm{C}$ to peak Temperature ( $\mathrm{T}_{\mathrm{p}}$ ) |  | 8 minutes Max. |
| Do not exceed |  | $260^{\circ} \mathrm{C}$ |



## PACKAGE MECHANICAL DATA



| Symbol | Dimensions In Millimeters |  | Dimensions In Inches |  |
| :---: | :---: | :---: | :---: | :---: |
|  | Min | Max | Min | Max |
| A | 0.510 | 0.770 | 0.020 | 0.031 |
| A1 | 0.500 | 0.700 | 0.020 | 0.028 |
| b | 0.250 | 0.350 | 0.010 | 0.014 |
| C | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 0.750 | 0.850 | 0.030 | 0.033 |
| E | 1.100 | 1.300 | 0.043 | 0.051 |
| E1 | 1.500 | 1.700 | 0.059 | 0.067 |
| E2 | 0.200 REF |  | 0.008 REF |  |
| L | 0.010 | 0.070 | 0.001 | 0.003 |
| 0 | $7^{\circ}$ REF |  | $7^{\circ}$ REF |  |

## Suggested Pad Layout



## Note:

1.Controlling dimension:in millimeters.
2.General tolerance: $\pm 0.05 \mathrm{~mm}$
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
| :---: | :---: | :---: |
| ESDXXXS1UB-MS | SOD-523 | 3000 |

## Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specificationsof any andall MSKSEMI Semiconductor products described orcontained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer'sproducts orequipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringementsof intellectual property rights or other rightsof third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor producthat you intend to use.


## X-ON Electronics

Largest Supplier of Electrical and Electronic Components
Click to view similar products for ESD Suppressors / TVS Diodes category:
Click to view products by MSKSEMI manufacturer:
Other Similar products are found below :
60KS200C D18V0L1B2LP-7B D5V0F4U5P5-7 DESD5V0U1BB-7 NTE4902 P4KE27CA P6KE11CA P6KE39CA-TP P6KE8.2A SA110CA SA60CA SA64CA SMBJ12CATR SMBJ33CATR SMBJ8.0A ESD101-B1-02ELS E6327 ESD105-B1-02EL E6327 ESD112-B102EL E6327 ESD119B1W01005E6327XTSA1 ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF 3.0SMCJ33CA-F 3.0SMCJ36A-F HSPC16701B02TP D3V3Q1B2DLP3-7 D55V0M1B2WS-7 DESD5V0U1BL-7B DRTR5V0U4SL-7 SCM1293A-04SO ESD200-B1-CSP0201 E6327 SM12-7 SMF8.0A-TP SMLJ45CA-TP CEN955 W/DATA 82350120560 VESD12A1A-HD1-GS08 CPDUR5V0R-HF CPDQC5V0U-HF CPDQC5V0USP-HF CPDQC5V0-HF D1213A-01LP4-7B D1213A-02WL-7 1SMB33CAT3G-XYZ MMAD1108/TR13 5KP100A 5KP15A 5KP18A 5KP48A

